

Product / Process Change Notification



N° 2019-005-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Change of wafer production location and wafer test location from Infineon Technologies Austria AG, Villach, Austria to Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia and change of wafer diameter from 6 inch to 8 inch affecting IFX25001ME V33

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **16th August 2019**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JEESD46**“, which stipulates:
“**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board: Dr. Eckart Süner
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

Product / Process Change Notification



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► **Products affected:** Please refer to attached affected product list 1_cip19005_A

► **Detailed Change Information:**

Subject: Change of wafer production location and wafer test location from Infineon Technologies Austria AG, Villach, Austria to Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia and change of wafer diameter from 6 inch to 8 inch affecting IFX25001ME V33

Reason: Due to continuously raising demand for Infineon automotive products exceeding the capacity in wafer fab Villach we have to transfer wafer fab and test location to the well-known FE location Kulim.

The 8" wafer manufacturing technology is the state of the art technology at INFINEON. Therefore the above mentioned products will be changed from 6" to 8".

The 5.0V fixed output-voltage variants of IFX25001-family are already running in DOPL_8" and the fixed 3.3 V variants are also already running in DOPL_8" for automotive application.

Description:

	<u>Old</u>	<u>New</u>
wafer production location and wafer test location	■ Infineon Technologies Austria AG, Villach, Austria	■ Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia
wafer diameter	■ 6 inch	■ 8 inch
SP Number	■ SP000623166	■ SP001586408

► **Product Identification:** Wafer lot numbers from Kulim start with 1Exxxxxx.
Traceability assured via date code and SP ordering number.

► **Impact of Change:** No change of product (form, fit, function) itself.

► **Attachments:** Affected product list 1_cip19005_A

► **Time Schedule:**

- Final qualification report: available
- First samples available: on request
- Intended start of delivery: 01-October-2019 or earlier after customer approval

If you have any questions, please do not hesitate to contact your local Sales office.

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Sales name	SP number	OPN	Package
IFX25001ME V33	SP000623166	IFX25001MEV33HTSA1	PG-SOT223-4